



## Media release

### **Cicor – successful launch of 3D-MID technology**

**Zurich, 21 December 2011. Headquartered in Boudry, Switzerland, Cicor (SIX Swiss Exchange: C1CN), a leading high-technology industrial group internationally active in the printed circuit boards, microelectronics and electronic solutions, has secured a number of orders in the field of 3D-MID technology. March 2011 saw Cicor drive this key pioneering technology with the inauguration of a technology centre at its headquarters in Boudry, Switzerland; the company is now harvesting successes from its endeavours in the market.**

One of the projects is a medical technology application that secures the connectivity of the device/system in its high-tech environment. The Cicor 3D-MID solution delivers a 40% reduction in volume and a 70% reduction in weight compared to the best existing conventional solution. Another project is in the field of security/data protection. This particular application concerns a high-security enclosure designed to protect sensitive data against unauthorised access. Cicor's 3D-MID solution delivers enhanced protection compared to conventional PCB solutions and meets the latest PCI PTS POI V3 standard (Payment Card Industry/PIN Transaction Security/Point of Interaction Version 3).

Further projects in the areas of medical technology, automotive engineering, security technology and 3D antennae are at an advanced stage of development. Implementation of these 3D-MID technology applications delivers greater miniaturisation and cost reductions and facilitates the integration of additional functions.

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**About 3D-MID technology** • 3D-MID (moulded interconnect devices) technology facilitates the integration of mechanical and electronic functions within a very small component. The electronic circuit is integrated into the casing, making it possible to achieve much more compact construction and much greater function density. More and more applications involving electrical and electro-optical circuits are made using 3D-MID technology. Use of moulded interconnect devices can drastically reduce process stages, assembly times and the number of separate components required. The main areas of application are in the automotive, medical technology, industrial technology and telecommunications sectors. Cicor Group offers all the process steps for manufacturing products using 3D-MID technology – from injection moulding to laser structuring and metallization, to set-up and interconnect technology, to assembly – and all from a single source.

**About Cicor** • Cicor is a globally active group of leading companies in the electronics industry. It is organized into four divisions: Printed Circuit Boards (PCB), Microelectronics (ME), Electronic Solutions (ES) and Asia. The group's companies provide complete outsourcing services and a broad range of technologies for the manufacture of highly complex PCBs, 3D-MID solutions, hybrids and electronic modules. With around 1300 employees at twelve production sites worldwide, the group supplies high-quality custom-made solutions to its clients in Europe, America and Asia. The shares of Cicor Technologies Ltd. are listed on the SIX Swiss Exchange (CICN). For further information please visit [www.cicor.com](http://www.cicor.com).